

Session 17 - Modeling, Reliability and Safety A Counter based ADC Non-linearity Measurement Circuit and Its Application to Reliability Testing

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Outline

- **Background**
- Proposed ADC Non-linearity Measurement Circuit
- o 65nm Test Chip Results
- Application to ADC Reliability Studies
- Conclusion



Analog-to-Digital Converter (ADC) Non-linearity



- Differential Non-Linearity (DNL) : Deviation from ideal width (1LSB)
- Integral Non-Linearity (INL) : Maximum deviation from ideal slope





Analog-to-Digital Converter (ADC) Non-linearity



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Pros.

 Simple setup
Does not require any onchip measurement circuits

Cons.

 Susceptible to package and on-chip noise





Conventional On-chip Test Setup







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Proposed In-situ DNL/INL Measurement Circuit (10b)



- Consists of a decoder block + array of 5b counters
- Counters corresponding to ADC codes increment their count value
- Count value instead of ADC output code → readout data volume↓





Proposed In-situ DNL/INL Measurement Circuit (10b)



- Separate ADC operation from data transfer operation
- Readout data volume↓ → small area overhead for storing data compared to SRAM array





Interleaved Design for Area Reduction



- 2-way interleaved design with only 50% counters
- Two separate tests for odd and even codes
- Stitch two test results for full DNL & INL histogram





Step 1: Odd Code Measurement







Step 2: Even Code Measurement







Implementation of DNL/INL Measurement Circuit



- Total 512 5-bit counters corresponding to ADC out D<9:1>
- Unit cell = 5b counter + scan-out circuits



Noise Immunity: Proposed vs. Off-chip Test

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Short-term Vth Instability



- Short-term Vth degradation and recovery occur due to Bias Temperature Instability (BTI)
- Time constant usually in the μs ~10's of μs order



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Impact on SAR-ADC Operation



Large input voltage difference → offset due to short-term
Vth shifts





Impact on SAR-ADC Operation



 If <u>input voltage difference < Vth shift difference</u> in the next step → incorrect decision





Impact on SAR-ADC Operation



- Manifests as a 1LSB error in the output code
 - Correct code pattern "0111" vs Incorrect code pattern "1000"
- Affects high-resolution, low-speed SAR-ADCs



Output Codes Vulnerable to Short-term BTI

	Conv. step						
Decimal		0	Bin	ary	DE		generating
value	D3		זט		DO	•••	error
127	0	0	<u> </u>	1	1	•••	D7
128	0	0	1	0	0	•••	
255	0	<u>0</u>	1	1		•••	D8
256	0	1	0	0	0	•••	
383	0	1	_ 0	1	1	•••	D7
384	Û	1	1	0	0	•••	
639	1	0	^ 0	1	1	•••	D7
640	1	0	1	0	0	•••	
767	1	()	1	1	1	•••	D 0
768	1	1	0	0	0	•••	
895	1	1	0	1	1	•••	D7
896	1	1	1	0	0	•••	

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- Prior arts identified vulnerable output codes
 - Error can occur from second conversion step
 - Odd codes ending with **0111**...
 - Even codes ending with **1000**...



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	Conv. step						
Decimal		Binary				generating	
value	D9	D8	D7	D6	D5	•••	error
127	0	0	_0	1	1	•••	D7
128	0	0	1	0	0		DI
255	0	ر ا	1	1	1	•••	
256	0	1	0	0	0	•••	Do
383	0	1	_ 0	1	1		D7
384	0	1	<u>\</u> 1	0	0		DI
639	1	0	_0	1	1		D7
640	1	0	<u>×1</u>	0	0	•••	Dī
767	1	ر ا	1	1	1	•••	Po
768	1	1	0	0	0	•••	
895	1	1	(0	1	1		DZ
896	1	1	<u>×1</u>	0	0		D7

- E.g. Error occurring in **D8** step
 - Large ΔV_{IN} @D9 + small ΔV_{IN} @D8
 - Odd codes ending with 0111

Adjacent even codes ending with 1000





	Conv. step						
Decimal	Binary						generating
value	D9	D8	D7	Ď6	D5	•••	error
127	0	0	0	1	1	•••	D7
128	0	0	1	0	0	•••	
255	0	_0	1	1	1	•••	D0
256	0	\$1	0	0	0	•••	Do
383	0	1	_ 0	1	1	•••	D7
384	0	1	1	0	0	•••	
639	1	0	0	1	1	•••	D7
640	1	0	1	0	0	•••	
767	1	~ 0	1	1	1		D0
768	1	<u>\$1</u>	0	0	0	•••	Do
895	1	1	0	1	1	•••	D7
896	1	1	<u>×1</u>	0	0	•••	

- E.g. Error occuring in **D7** step
 - Large ΔV_{IN} @D9, D8 + small ΔV_{IN} @D7
 - Odd codes ending with 0111

Adjacent even codes ending with 1000



Stress Equalization, Variable Duty Cycle



- Stress equalization using switched source node
- Ratio between stress and recovery times can be varied
 - Multi-phase VCO used to generate different duty cycles





- Shorter duty cycle → shorter BTI stress & longer recovery time
 - DNL increases (or decreases) for odd (or even) vulnerable codes
 - Subtle shift because comparators use IO input devices



10b DNL vs. Clock Frequency



 Short term Vth instability effect less at higher frequencies due to reduced stress time



10b DNL vs. Comparator Type



Short term Vth instability effect more pronounce for PMOS input comparator



Chip Summary & Die Photo

L				
D I	250µm	Proc	ess	65nm CMOS
385µm		Core / IO	supply	1.0V / 2.5V
	8	ADC res	olution	10-bit
	CDAC	DNL (max)	vs Con. (w/o SRAM)	0.88 LSB (1.23 LSB improv.)
		Read Out Data Volume	vs Con.	1/64 (for 32 samples/code)
20um	In-situ INL/DNL	Tr. count o measurem	of on-chip ent block	94K (Counters only)
24	Meas. Block	DN	IL	+0.34 / -0.88 LSB @ 1MHz
		IN	L	+1.67 / -1.41 LSB @ 1MHz
	635µm	Total ch	ip area	0.57mm ²





Conclusion

- Counter based measurement circuit is demonstrated for precise characterization of ADC DNL and INL
- Using the proposed method, short-term BTI is studied in a 10-bit SAR-ADC in 65nm CMOS
- Subtle DNL shifts can be accurately measured using the proposed method

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